



PATENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450



Sir:

The patent application of

Inventor(s): KURAMOTO ET AL

For: SOLDER BALL ASSEMBLY, A METHOD FOR ITS
MANUFACTURE, AND A METHOD OF FORMING SOLDER
BUMPS

is attached for filing.

[X] This application is being filed without a declaration or
fee.

[X] This application claims the priority of Japanese Patent
Application No. 2002-226340 filed on August 2, 2002.

[X] An Information Disclosure Statement is attached.

Respectfully submitted,

Michael Tobias
Registration Number 32,948

#40
1717 K Street, N.W., Suite 613
Washington, D.C. 20036
Telephone: (301) 587-6541
Facsimile: (301) 587-6623
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